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A semiconductor device according to claim 1, where
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1 10. A semiconductor device according to claim 6, wherein said
2 chip electrodes comprise at least one kind of terminals selected from
3 ground, power-source and signal terminals of said semiconductor chip.

conductor
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[illegible]

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Contd

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1 15. A semiconductor device according to claim 11, wherein said
2 chip electrodes comprise at least one kind of terminals selected from
3 ground, power-source and signal terminals of said semiconductor chip.

MA 5

chip display

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Two or more
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10 17. A semiconductor device according to claim 16, wherein said
11 chip electrodes are arranged from an edge of said semiconductor chip
12 toward its inner side.

1 18. A semiconductor device according to claim 16, wherein said
2 chip electrodes are arranged parallel to an edge of said semiconductor
3 chip and said wiring is bent at at least one position.

1 19. A semiconductor device according to claim 16, wherein said
2 chip electrodes are arranged parallel to an edge of said semiconductor
3 chip and said wiring has an end width larger than an inter-electrode
4 distance between said chip electrodes.

1 20. A semiconductor device according to claim 16, wherein said
2 chip electrodes comprise at least one kind of terminals selected from
3 ground, power-source and signal terminals of said semiconductor chip.

[illegible]

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add D^5